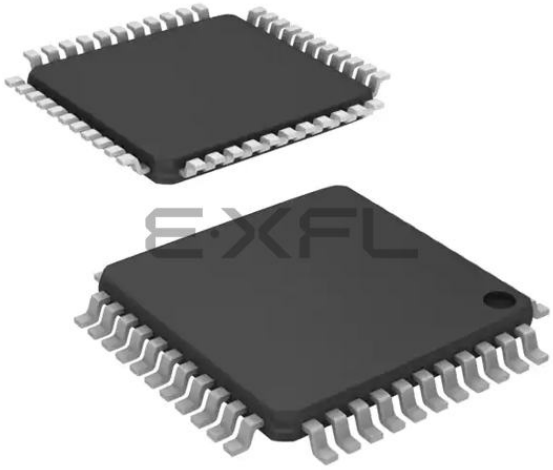


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	50MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	33
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx270f256dt-50i-pt

2.8.1 CRYSTAL OSCILLATOR DESIGN CONSIDERATION

The following example assumptions are used to calculate the Primary Oscillator loading capacitor values:

- CIN = PIC32_OSC2_Pin Capacitance = ~4-5 pF
- COUT = PIC32_OSC1_Pin Capacitance = ~4-5 pF
- C1 and C2 = XTAL manufacturing recommended loading capacitance
- Estimated PCB stray capacitance, (i.e.,12 mm length) = 2.5 pF

EXAMPLE 2-1: CRYSTAL LOAD CAPACITOR CALCULATION

Crystal manufacturer recommended: $C1 = C2 = 15\ pF$

Therefore:

$$C_{LOAD} = \{([C_{IN} + C1] * [C_{OUT} + C2]) / [C_{IN} + C1 + C2 + C_{OUT}] \} + \text{estimated oscillator PCB stray capacitance}$$
$$= \{([5 + 15][5 + 15]) / [5 + 15 + 15 + 5] \} + 2.5\ pF$$
$$= \{([20][20]) / [40] \} + 2.5$$
$$= 10 + 2.5 = 12.5\ pF$$

Rounded to the nearest standard value or 12 pF in this example for Primary Oscillator crystals "C1" and "C2".

The following tips are used to increase oscillator gain, (i.e., to increase peak-to-peak oscillator signal):

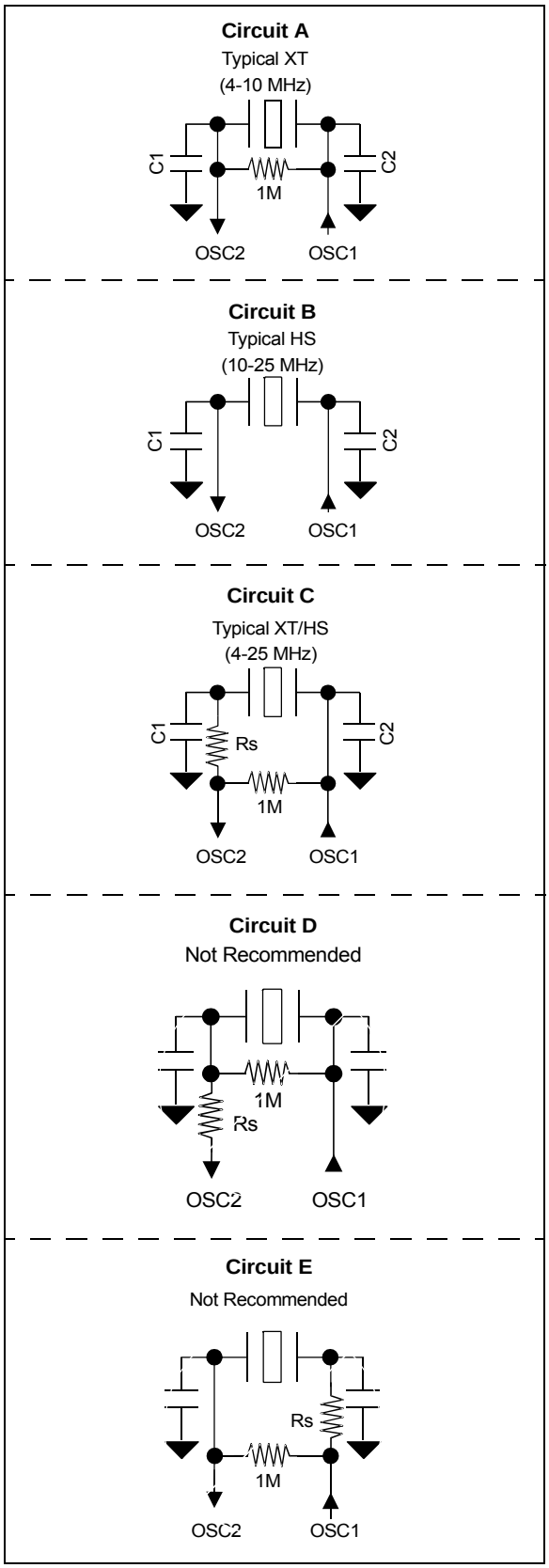
- Select a crystal with a lower "minimum" power drive rating
- Select an crystal oscillator with a lower XTAL manufacturing "ESR" rating.
- Add a parallel resistor across the crystal. The smaller the resistor value the greater the gain. It is recommended to stay in the range of 600k to 1M
- C1 and C2 values also affect the gain of the oscillator. The lower the values, the higher the gain.
- C2/C1 ratio also affects gain. To increase the gain, make C1 slightly smaller than C2, which will also help start-up performance.

Note: Do not add excessive gain such that the oscillator signal is clipped, flat on top of the sine wave. If so, you need to reduce the gain or add a series resistor, RS, as shown in circuit "C" in Figure 2-4. Failure to do so will stress and age the crystal, which can result in an early failure. Adjust the gain to trim the max peak-to-peak to ~VDD-0.6V. When measuring the oscillator signal you must use a FET scope probe or a probe with ≤ 1.5 pF or the scope probe itself will unduly change the gain and peak-to-peak levels.

2.8.1.1 Additional Microchip References

- AN588 *"PICmicro® Microcontroller Oscillator Design Guide"*
- AN826 *"Crystal Oscillator Basics and Crystal Selection for rfPIC™ and PICmicro® Devices"*
- AN849 *"Basic PICmicro® Oscillator Design"*

FIGURE 2-4: PRIMARY CRYSTAL OSCILLATOR CIRCUIT RECOMMENDATIONS



The MIPS architecture defines that the result of a multiply or divide operation be placed in the HI and LO registers. Using the Move-From-HI (MFHI) and Move-From-LO (MFLO) instructions, these values can be transferred to the General Purpose Register file.

In addition to the HI/LO targeted operations, the MIPS32® architecture also defines a multiply instruction, MUL, which places the least significant results in the primary register file instead of the HI/LO register pair. By avoiding the explicit MFLO instruction required when using the LO register, and by supporting multiple destination registers, the throughput of multiply-intensive operations is increased.

Two other instructions, Multiply-Add (MADD) and Multiply-Subtract (MSUB), are used to perform the multiply-accumulate and multiply-subtract operations. The MADD instruction multiplies two numbers and then adds the product to the current contents of the HI and LO registers. Similarly, the MSUB instruction multiplies two operands and then subtracts the product from the HI and LO registers. The MADD and MSUB operations are commonly used in DSP algorithms.

3.2.3 SYSTEM CONTROL COPROCESSOR (CP0)

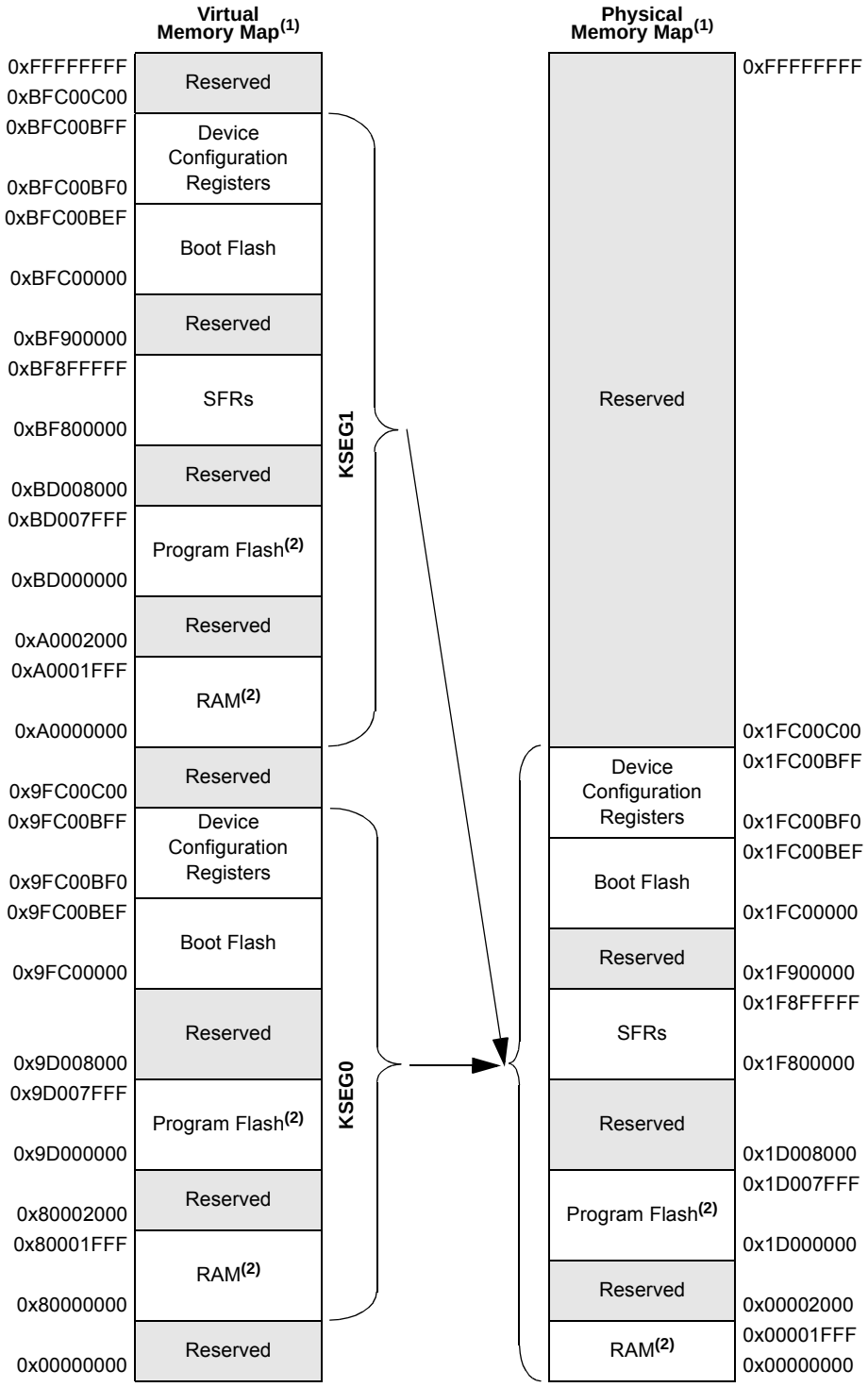
In the MIPS architecture, CP0 is responsible for the virtual-to-physical address translation, the exception control system, the processor's diagnostics capability, the operating modes (Kernel, User and Debug) and whether interrupts are enabled or disabled. Configuration information, such as presence of options like MIPS16e, is also available by accessing the CP0 registers, listed in Table 3-2.

TABLE 3-2: COPROCESSOR 0 REGISTERS

Register Number	Register Name	Function
0-6	Reserved	Reserved in the PIC32MX1XX/2XX family core.
7	HWREna	Enables access via the RDHWR instruction to selected hardware registers.
8	BadVAddr(1)	Reports the address for the most recent address-related exception.
9	Count(1)	Processor cycle count.
10	Reserved	Reserved in the PIC32MX1XX/2XX family core.
11	Compare(1)	Timer interrupt control.
12	Status(1)	Processor status and control.
12	IntCtl(1)	Interrupt system status and control.
12	SRSCtl(1)	Shadow register set status and control.
12	SRSMap(1)	Provides mapping from vectored interrupt to a shadow set.
13	Cause(1)	Cause of last general exception.
14	EPC(1)	Program counter at last exception.
15	PRId	Processor identification and revision.
15	EBASE	Exception vector base register.
16	Config	Configuration register.
16	Config1	Configuration Register 1.
16	Config2	Configuration Register 2.
16	Config3	Configuration Register 3.
17-22	Reserved	Reserved in the PIC32MX1XX/2XX family core.
23	Debug(2)	Debug control and exception status.
24	DEPC(2)	Program counter at last debug exception.
25-29	Reserved	Reserved in the PIC32MX1XX/2XX family core.
30	ErrorEPC(1)	Program counter at last error.
31	DESAVE(2)	Debug handler scratchpad register.

Note 1: Registers used in exception processing.
2: Registers used during debug.

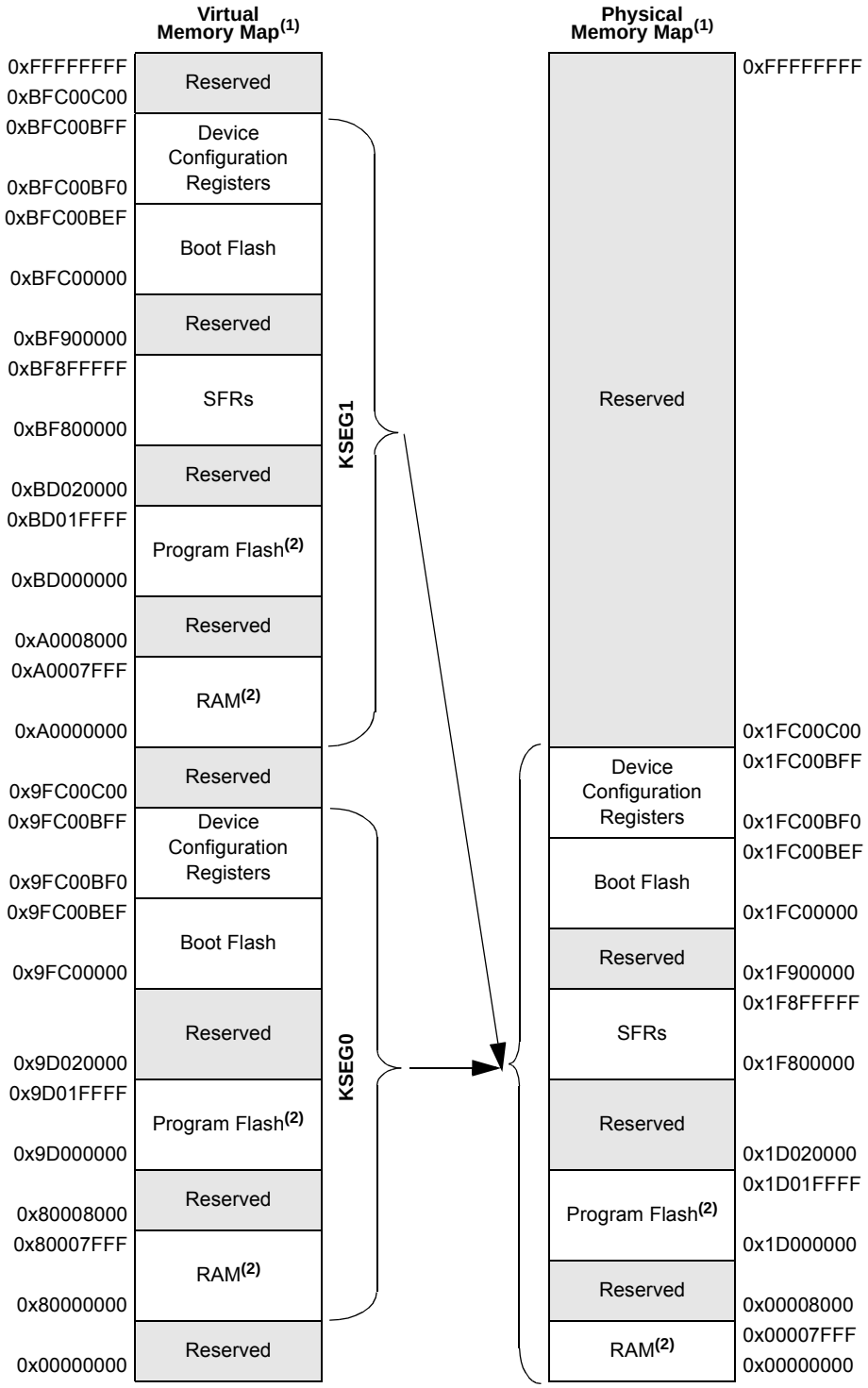
FIGURE 4-2: MEMORY MAP ON RESET FOR PIC32MX120/220 DEVICES (8 KB RAM, 32 KB FLASH)



Note 1: Memory areas are not shown to scale.

2: The size of this memory region is programmable (see **Section 3. "Memory Organization"** (DS60001115) in the *"PIC32 Family Reference Manual"*) and can be changed by initialization code provided by end-user development tools (refer to the specific development tool documentation for information).

FIGURE 4-4: MEMORY MAP ON RESET FOR PIC32MX150/250 DEVICES (32 KB RAM, 128 KB FLASH)



Note 1: Memory areas are not shown to scale.

2: The size of this memory region is programmable (see **Section 3. "Memory Organization"** (DS60001115) in the *"PIC32 Family Reference Manual"*) and can be changed by initialization code provided by end-user development tools (refer to the specific development tool documentation for information).

REGISTER 5-4: NVMDATA: FLASH PROGRAM DATA REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMDATA<31:24>							
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMDATA<23:16>							
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMDATA<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMDATA<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-0 **NVMDATA<31:0>:** Flash Programming Data bits

Note: The bits in this register are only reset by a Power-on Reset (POR).

REGISTER 5-5: NVMSRCADDR: SOURCE DATA ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMSRCADDR<31:24>							
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMSRCADDR<23:16>							
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMSRCADDR<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	NVMSRCADDR<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-0 **NVMSRCADDR<31:0>:** Source Data Address bits

The system physical address of the data to be programmed into the Flash when the NVMOP<3:0> bits (NVMCON<3:0>) are set to perform row programming.

REGISTER 9-9: DCHxINT: DMA CHANNEL 'x' INTERRUPT CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHSDIE	CHSHIE	CHDDIE	CHDHIE	CHBCIE	CHCCIE	CHTAIE	CHERIE
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHSDIF	CHSHIF	CHDDIF	CHDHIF	CHBCIF	CHCCIF	CHTAIF	CHERIF

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-24 **Unimplemented:** Read as '0'

bit 23 **CHSDIE:** Channel Source Done Interrupt Enable bit
- 1 = Interrupt is enabled
- 0 = Interrupt is disabled

bit 22 **CHSHIE:** Channel Source Half Empty Interrupt Enable bit
- 1 = Interrupt is enabled
- 0 = Interrupt is disabled

bit 21 **CHDDIE:** Channel Destination Done Interrupt Enable bit
- 1 = Interrupt is enabled
- 0 = Interrupt is disabled

bit 20 **CHDHIE:** Channel Destination Half Full Interrupt Enable bit
- 1 = Interrupt is enabled
- 0 = Interrupt is disabled

bit 19 **CHBCIE:** Channel Block Transfer Complete Interrupt Enable bit
- 1 = Interrupt is enabled
- 0 = Interrupt is disabled

bit 18 **CHCCIE:** Channel Cell Transfer Complete Interrupt Enable bit
- 1 = Interrupt is enabled
- 0 = Interrupt is disabled

bit 17 **CHTAIE:** Channel Transfer Abort Interrupt Enable bit
- 1 = Interrupt is enabled
- 0 = Interrupt is disabled

bit 16 **CHERIE:** Channel Address Error Interrupt Enable bit
- 1 = Interrupt is enabled
- 0 = Interrupt is disabled

bit 15-8 **Unimplemented:** Read as '0'

bit 7 **CHSDIF:** Channel Source Done Interrupt Flag bit
- 1 = Channel Source Pointer has reached end of source (CHSPTR = CHSSIZ)
- 0 = No interrupt is pending

bit 6 **CHSHIF:** Channel Source Half Empty Interrupt Flag bit
- 1 = Channel Source Pointer has reached midpoint of source (CHSPTR = CHSSIZ/2)
- 0 = No interrupt is pending

bit 5 **CHDDIF:** Channel Destination Done Interrupt Flag bit
- 1 = Channel Destination Pointer has reached end of destination (CHDPTR = CHDSIZ)
- 0 = No interrupt is pending

TABLE 11-7: PERIPHERAL PIN SELECT OUTPUT REGISTER MAP

Virtual Address (BF80_#)	Register Name	Bit Range	Bits															All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
FB00	RPA0R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPA0<3:0>				0000
FB04	RPA1R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPA1<3:0>				0000
FB08	RPA2R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPA2<3:0>				0000
FB0C	RPA3R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPA3<3:0>				0000
FB10	RPA4R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPA4<3:0>				0000
FB20	RPA8R(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPA8<3:0>				0000
FB24	RPA9R(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPA9<3:0>				0000
FB2C	RPB0R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPB0<3:0>				0000
FB30	RPB1R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPB1<3:0>				0000
FB34	RPB2R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPB2<3:0>				0000
FB38	RPB3R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPB3<3:0>				0000
FB3C	RPB4R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPB4<3:0>				0000
FB40	RPB5R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPB5<3:0>				0000
FB44	RPB6R(2)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPB6<3:0>				0000
FB48	RPB7R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPB7<3:0>				0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register is only available on 44-pin devices.
2: This register is only available on PIC32MX1XX devices.
3: This register is only available on 36-pin and 44-pin devices.

REGISTER 11-3: CNCONx: CHANGE NOTICE CONTROL FOR PORTx REGISTER (x = A, B, C)

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
	ON	—	SIDL	—	—	—	—	—
7:0	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ON:** Change Notice (CN) Control ON bit
- 1 = CN is enabled
- 0 = CN is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **SIDL:** Stop in Idle Control bit
- 1 = Idle mode halts CN operation
- 0 = Idle does not affect CN operation

bit 12-0 **Unimplemented:** Read as '0'

REGISTER 12-1: T1CON: TYPE A TIMER CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	R/W-0	R/W-0	R-0	U-0	U-0	U-0
	ON(1)	—	SIDL	TWDIS	TWIP	—	—	—
7:0	R/W-0	U-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	U-0
	TGATE	—	TCKPS<1:0>		—	TSYNC	TCS	—

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ON:** Timer On bit(1)
- 1 = Timer is enabled
- 0 = Timer is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **SIDL:** Stop in Idle Mode bit
- 1 = Discontinue module operation when the device enters Idle mode
- 0 = Continue module operation when the device enters Idle mode

bit 12 **TWDIS:** Asynchronous Timer Write Disable bit
- 1 = Writes to Timer1 are ignored until pending write operation completes
- 0 = Back-to-back writes are enabled (Legacy Asynchronous Timer functionality)

bit 11 **TWIP:** Asynchronous Timer Write in Progress bit

In Asynchronous Timer mode:
- 1 = Asynchronous write to the Timer1 register in progress
- 0 = Asynchronous write to Timer1 register is complete

In Synchronous Timer mode:
This bit is read as '0'.

bit 10-8 **Unimplemented:** Read as '0'

bit 7 **TGATE:** Timer Gated Time Accumulation Enable bit

When TCS = 1:
This bit is ignored.

When TCS = 0:
- 1 = Gated time accumulation is enabled
- 0 = Gated time accumulation is disabled

bit 6 **Unimplemented:** Read as '0'

bit 5-4 **TCKPS<1:0>:** Timer Input Clock Prescale Select bits
- 11 = 1:256 prescale value
- 10 = 1:64 prescale value
- 01 = 1:8 prescale value
- 00 = 1:1 prescale value

Note 1: When using 1:1 PBCmLK divisor, the user's software should not read/write the peripheral SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

18.0 INTER-INTEGRATED CIRCUIT (I^2C)

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 24. "Inter-Integrated Circuit (I^2C)"** (DS60001116), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

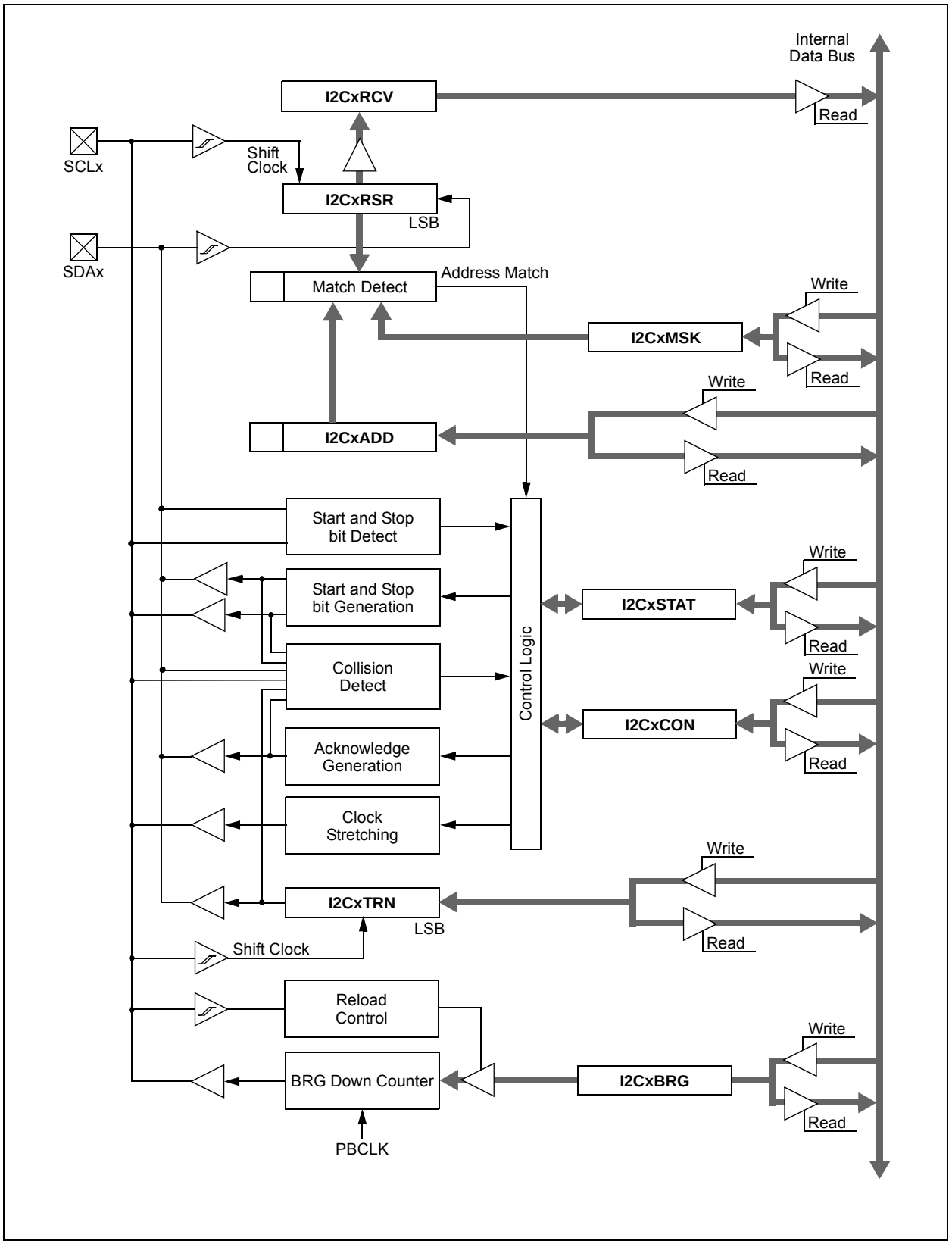
The I^2C module provides complete hardware support for both Slave and Multi-Master modes of the I^2C serial communication standard. Figure 18-1 illustrates the I^2C module block diagram.

Each I^2C module has a 2-pin interface: the SCLx pin is clock and the SDAx pin is data.

Each I^2C module offers the following key features:

- I^2C interface supporting both master and slave operation
- I^2C Slave mode supports 7-bit and 10-bit addressing
- I^2C Master mode supports 7-bit and 10-bit addressing
- I^2C port allows bidirectional transfers between master and slaves
- Serial clock synchronization for the I^2C port can be used as a handshake mechanism to suspend and resume serial transfer (SCLREL control)
- I^2C supports multi-master operation; detects bus collision and arbitrates accordingly
- Provides support for address bit masking

FIGURE 18-1: I²C BLOCK DIAGRAM



20.1 PMP Control Registers

TABLE 20-1: PARALLEL MASTER PORT REGISTER MAP

Virtual Address (BF80_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
7000	PMCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	ADRMUX<1:0>		PMPTTL	PTWREN	PTRDEN	CSF<1:0>		ALP	—	CS1P	—	WRSP	RDSP	0000
7010	PMMODE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	BUSY	IRQM<1:0>		INCM<1:0>		—	MODE<1:0>		WAITB<1:0>		WAITM<3:0>				WAITE<1:0>		0000
7020	PMADDR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	CS1 / ADDR14	—	—	—	ADDR<10:0>											0000
7030	PMDOUT	31:16	DATAOUT<31:0>																0000
		15:0																	0000
7040	PMDIN	31:16	DATAIN<31:0>																0000
		15:0																	0000
7050	PMAEN	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	PTEN14	—	—	—	PTEN<10:0>											0000
7060	PMSTAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	IBF	IBOV	—	—	IB3F	IB2F	IB1F	IB0F	OBE	OBUF	—	—	OB3E	OB2E	OB1E	OB0E	008F

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

REGISTER 22-4: AD1CHS: ADC INPUT SELECT REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
	CH0NB	—	—	—	CH0SB<3:0>			
23:16	R/W-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
	CH0NA	—	—	—	CH0SA<3:0>			
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31 **CH0NB:** Negative Input Select bit for Sample B
1 = Channel 0 negative input is AN1
0 = Channel 0 negative input is VREFL

bit 30-28 **Unimplemented:** Read as '0'

bit 27-24 **CH0SB<3:0>:** Positive Input Select bits for Sample B
1111 = Channel 0 positive input is Open(1)
1110 = Channel 0 positive input is IVREF(2)
1101 = Channel 0 positive input is CTMU temperature sensor (CTMUT)(3)
1100 = Channel 0 positive input is AN12(4)
•
•
•
0001 = Channel 0 positive input is AN1
0000 = Channel 0 positive input is AN0

bit 23 **CH0NA:** Negative Input Select bit for Sample A Multiplexer Setting(2)
1 = Channel 0 negative input is AN1
0 = Channel 0 negative input is VREFL

bit 22-20 **Unimplemented:** Read as '0'

bit 19-16 **CH0SA<3:0>:** Positive Input Select bits for Sample A Multiplexer Setting
1111 = Channel 0 positive input is Open(1)
1110 = Channel 0 positive input is IVREF(2)
1101 = Channel 0 positive input is CTMU temperature (CTMUT)(3)
1100 = Channel 0 positive input is AN12(4)
•
•
•
0001 = Channel 0 positive input is AN1
0000 = Channel 0 positive input is AN0

bit 15-0 **Unimplemented:** Read as '0'

Note 1: This selection is only used with CTMU capacitive and time measurement.
2: See **Section 24.0 "Comparator Voltage Reference (CVREF)"** for more information.
3: See **Section 25.0 "Charge Time Measurement Unit (CTMU)"** for more information.
4: AN12 is only available on 44-pin devices. AN6-AN8 are not available on 28-pin devices.

REGISTER 27-2: DEVCFG1: DEVICE CONFIGURATION WORD 1 (CONTINUED)

bit 15-14 **FCKSM<1:0>:** Clock Switching and Monitor Selection Configuration bits
- 1x = Clock switching is disabled, Fail-Safe Clock Monitor is disabled
- 01 = Clock switching is enabled, Fail-Safe Clock Monitor is disabled
- 00 = Clock switching is enabled, Fail-Safe Clock Monitor is enabled

bit 13-12 **FPBDIV<1:0>:** Peripheral Bus Clock Divisor Default Value bits
- 11 = PBCLK is SYSCLK divided by 8
- 10 = PBCLK is SYSCLK divided by 4
- 01 = PBCLK is SYSCLK divided by 2
- 00 = PBCLK is SYSCLK divided by 1

bit 11 **Reserved:** Write '1'

bit 10 **OSCIOFNC:** CLKO Enable Configuration bit
- 1 = CLKO output disabled
- 0 = CLKO output signal active on the OSCO pin; Primary Oscillator must be disabled or configured for the External Clock mode (EC) for the CLKO to be active (POSCMOD<1:0> = 11 or 00)

bit 9-8 **POSCMOD<1:0>:** Primary Oscillator Configuration bits
- 11 = Primary Oscillator is disabled
- 10 = HS Oscillator mode is selected
- 01 = XT Oscillator mode is selected
- 00 = External Clock mode is selected

bit 7 **IESO:** Internal External Switchover bit
- 1 = Internal External Switchover mode is enabled (Two-Speed Start-up is enabled)
- 0 = Internal External Switchover mode is disabled (Two-Speed Start-up is disabled)

bit 6 **Reserved:** Write '1'

bit 5 **FSOSCEN:** Secondary Oscillator Enable bit
- 1 = Enable Secondary Oscillator
- 0 = Disable Secondary Oscillator

bit 4-3 **Reserved:** Write '1'

bit 2-0 **FNOSC<2:0>:** Oscillator Selection bits
- 111 = Fast RC Oscillator with divide-by-N (FRCDIV)
- 110 = FRCDIV16 Fast RC Oscillator with fixed divide-by-16 postscaler
- 101 = Low-Power RC Oscillator (LPRC)
- 100 = Secondary Oscillator (SOSC)
- 011 = Primary Oscillator (POSC) with PLL module (XT+PLL, HS+PLL, EC+PLL)
- 010 = Primary Oscillator (XT, HS, EC)(1)
- 001 = Fast RC Oscillator with divide-by-N with PLL module (FRCDIV+PLL)
- 000 = Fast RC Oscillator (FRC)

Note 1: Do not disable the POSC (POSCMOD = 11) when using this oscillator source.

TABLE 30-10: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
DO10	VOL	**Output Low Voltage** I/O Pins	—	—	0.4	V	IOL ≤ 10 mA, VDD = 3.3V
DO20	VOH	**Output High Voltage** I/O Pins	1.5(1)	—	—	V	IOH ≥ -14 mA, VDD = 3.3V
			2.0(1)	—	—		IOH ≥ -12 mA, VDD = 3.3V
			2.4	—	—		IOH ≥ -10 mA, VDD = 3.3V
			3.0(1)	—	—		IOH ≥ -7 mA, VDD = 3.3V

Note 1: Parameters are characterized, but not tested.

TABLE 30-11: ELECTRICAL CHARACTERISTICS: BOR

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.(1)**	**Typical**	**Max.**	**Units**	**Conditions**
BO10	VBOR	BOR Event on VDD transition high-to-low(2)	2.0	—	2.3	V	—

Note 1: Parameters are for design guidance only and are not tested in manufacturing.

2: Overall functional device operation at VBORMIN < VDD < VDDMIN is tested, but not characterized. All device Analog modules, such as ADC, etc., will function, but with degraded performance below VDDMIN.

TABLE 30-17: EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical(1)**	**Max.**	**Units**	**Conditions**
OS10	FOSC	External CLKI Frequency (External clocks allowed only in EC and ECPLL modes)	DC 4	— —	40 40	MHz MHz	EC **(Note 4)** ECPLL **(Note 3)**
OS11		Oscillator Crystal Frequency	3	—	10	MHz	XT **(Note 4)**
OS12			4	—	10	MHz	XTPLL **(Notes 3,4)**
OS13			10	—	25	MHz	HS **(Note 5)**
OS14			10	—	25	MHz	HSPLL **(Notes 3,4)**
OS15			32	32.768	100	kHz	SOSC **(Note 4)**
OS20	TOSC	TOSC = 1/FOSC = TCY **(Note 2)**	—	—	—	—	See parameter OS10 for FOSC value
OS30	TOSL, TOSH	External Clock In (OSC1) High or Low Time	0.45 x TOSC	—	—	ns	EC **(Note 4)**
OS31	TOSR, TOSF	External Clock In (OSC1) Rise or Fall Time	—	—	0.05 x TOSC	ns	EC **(Note 4)**
OS40	TOST	Oscillator Start-up Timer Period (Only applies to HS, HSPLL, XT, XTPLL and SOSC Clock Oscillator modes)	—	1024	—	TOSC	**(Note 4)**
OS41	TFSCM	Primary Clock Fail Safe Time-out Period	—	2	—	ms	**(Note 4)**
OS42	GM	External Oscillator Transconductance (Primary Oscillator only)	—	12	—	mA/V	VDD = 3.3V, TA = +25°C **(Note 4)**

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are characterized but are not tested.

2: Instruction cycle period (TCY) equals the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKI pin.

3: PLL input requirements: 4 MHz ≤ FPLLIN ≤ 5 MHz (use PLL prescaler to reduce FOSC). This parameter is characterized, but tested at 10 MHz only at manufacturing.

4: This parameter is characterized, but not tested in manufacturing.

FIGURE 30-12: SPIx MODULE SLAVE MODE (CKE = 0) TIMING CHARACTERISTICS

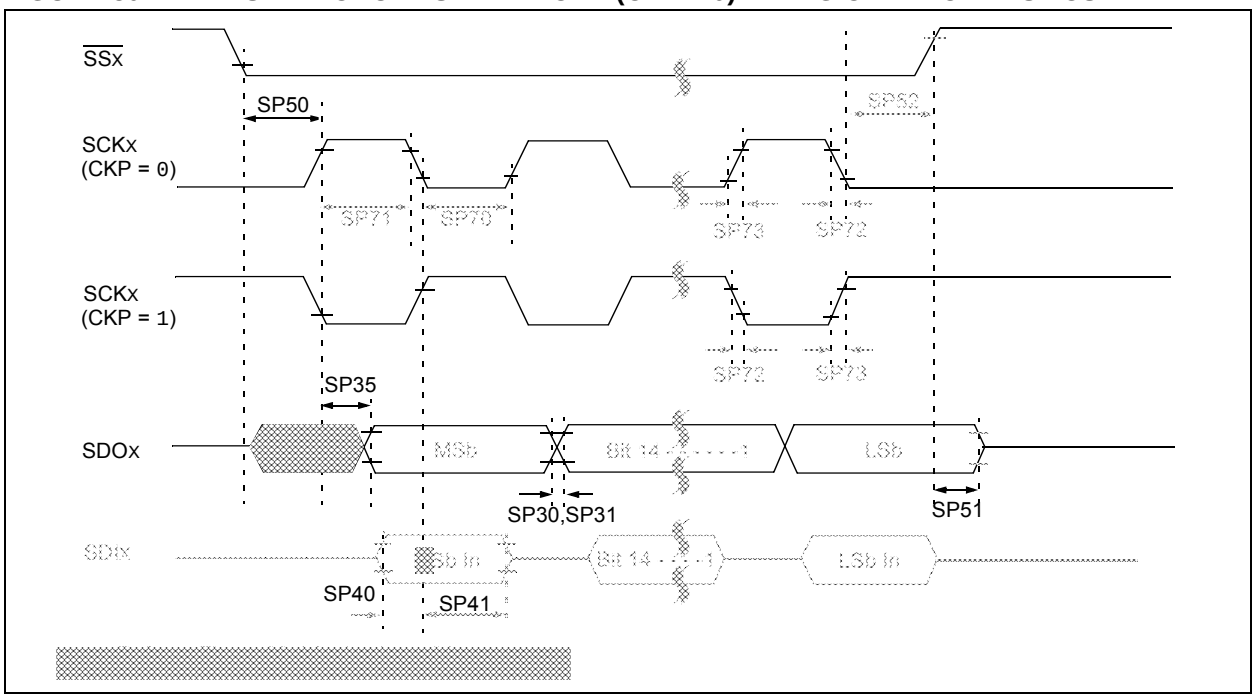


TABLE 30-30: SPIx MODULE SLAVE MODE (CKE = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	TscL	SCKx Input Low Time **(Note 3)**	Tsck/2	—	—	ns	—
SP71	TscH	SCKx Input High Time **(Note 3)**	Tsck/2	—	—	ns	—
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See parameter DO32
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See parameter DO31
SP30	TdoF	SDOx Data Output Fall Time **(Note 4)**	—	—	—	ns	See parameter DO32
SP31	TdoR	SDOx Data Output Rise Time **(Note 4)**	—	—	—	ns	See parameter DO31
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	15	ns	VDD > 2.7V
			—	—	20	ns	VDD < 2.7V
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP50	TssL2scH, TssL2scL	$\overline{SSx}$ ↓ to SCKx ↑ or SCKx Input	175	—	—	ns	—
SP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance **(Note 3)**	5	—	25	ns	—
SP52	TscH2ssH TscL2ssH	$\overline{SSx}$ after SCKx Edge	Tsck + 20	—	—	ns	—

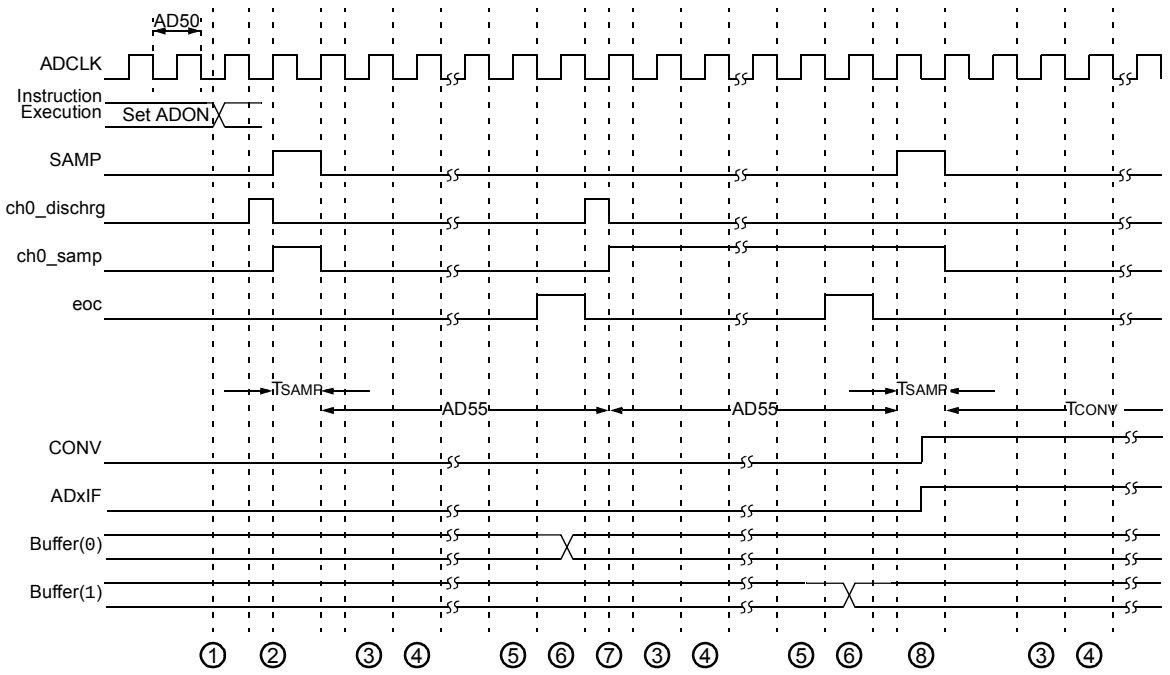
Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 50 ns.

4: Assumes 50 pF load on all SPIx pins.

FIGURE 30-19: ANALOG-TO-DIGITAL CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (ASAM = 1, SSRC<2:0> = 111, SAMC<4:0> = 00001)



(1) – Software sets ADxCON. ADON to start AD operation.

(2) – Sampling starts after discharge period. TSAMP is described in **Section 17. "10-bit Analog-to-Digital Converter (ADC)"** (DS60001104).

(3) – Convert bit 9.

(4) – Convert bit 8.

(5) – Convert bit 0.

(6) – One TAD for end of conversion.

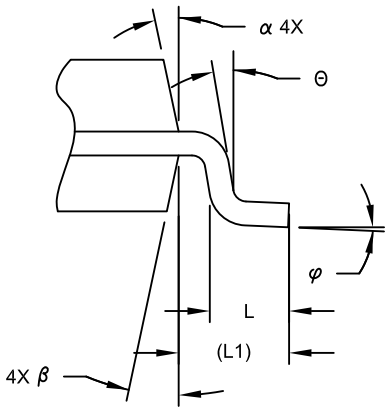
(7) – Begin conversion of next channel.

(8) – Sample for time specified by SAMC<4:0>.

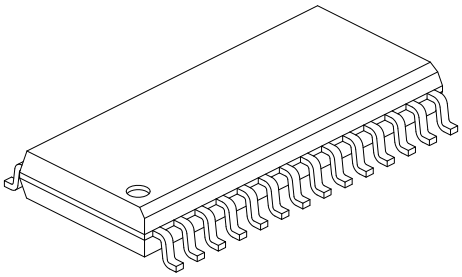
NOTES:

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E		10.30 BSC	
Molded Package Width	E1		7.50 BSC	
Overall Length	D		17.90 BSC	
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1		1.40 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.18	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing C04-052C Sheet 2 of 2